

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65LVDS387DGG	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGG.B	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGGG4	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGGR	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGGR.B	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGGRG4	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	-	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS387DGGRG4.B	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS387
SN65LVDS389DBT	Active	Production	TSSOP (DBT) 38	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBT.B	Active	Production	TSSOP (DBT) 38	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBTG4	Active	Production	TSSOP (DBT) 38	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBTR	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBTR.B	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBTRG4	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS389DBTRG4.B	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	LVDS389
SN65LVDS391D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391D.B	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391DG4	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391DR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391DRG4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391PW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391PW.B	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391PWG4	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN65LVDS391PWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVDS391
SN75LVDS387DGG	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS387DGG.B	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS387DGGG4	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS387DGGG4.B	Active	Production	TSSOP (DGG) 64	25 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN75LVDS387DGGR	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS387DGGR.B	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS387DGGRG4	Active	Production	TSSOP (DGG) 64	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS387
SN75LVDS389DBT	Active	Production	TSSOP (DBT) 38	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS389
SN75LVDS389DBT.B	Active	Production	TSSOP (DBT) 38	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS389
SN75LVDS389DBTR	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS389
SN75LVDS389DBTR.B	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS389
SN75LVDS389DBTRG4	Active	Production	TSSOP (DBT) 38	2000 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 70	75LVDS389
SN75LVDS391D	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75LVDS391
SN75LVDS391D.B	Active	Production	SOIC (D) 16	40 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75LVDS391
SN75LVDS391DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75LVDS391
SN75LVDS391DR.B	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	75LVDS391
SN75LVDS391PW	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS391
SN75LVDS391PW.B	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS391
SN75LVDS391PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS391
SN75LVDS391PWR.B	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	DS391

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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